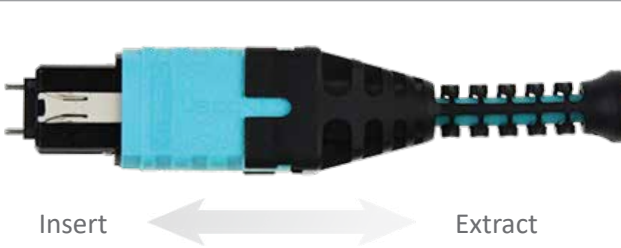


DirectConec™ Push-Pull System

DirectConec™ push-pull technology enables the highest functional density in fiber cabling environments without the need for pull tabs or field tools. US Conec has now incorporated this technology into multiple connector platforms including MTP® PRO, ELiMENT™ MDC and Duplex LC Uniboot, and the highest fiber density MMC connectors.

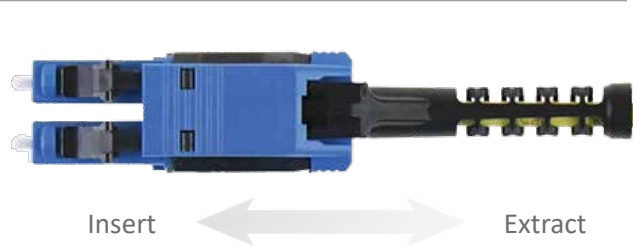
Features:

- Effortless insertion and extraction while accessing the strain relief boot
- Simple functional access in high fiber count areas for increased usable density
- Supports full Telcordia, TIA and IEC mechanical loading and durability requirements



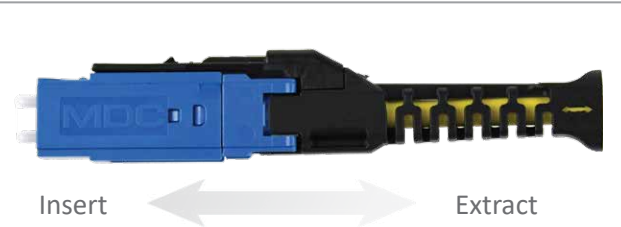
MTP® PRO

- Premier field/factory configurability
 - Secure, simple pin change
 - Effortless polarity change
- Reduced debris system for seamless installations



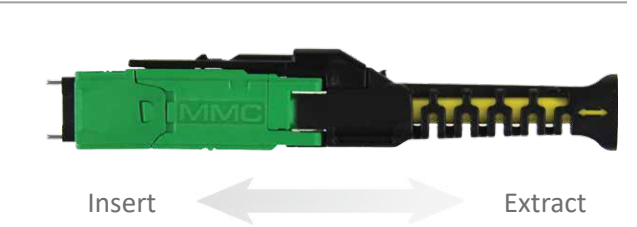
ELiMENT™ Duplex LC Uniboot

- Simple toolless polarity change
- Low profile design for maximum density
- Compatible with all industry compliant transceivers



ELiMENT™ MDC

- Premier very small form factor (VSFF) duplex connector with 3x density over LC
- PC and APC polarity change without exposed fibers
- 1.25 mm ferrule technology



MMC

- Premier very small form factor (VSFF) multi-fiber connector with 3x density over MPO
- State of the art TMT ferrule technology supporting 16, 8 and 4 fiber applications on 250µm pitch
- IEC Grade B performance
- SM APC and MM APC